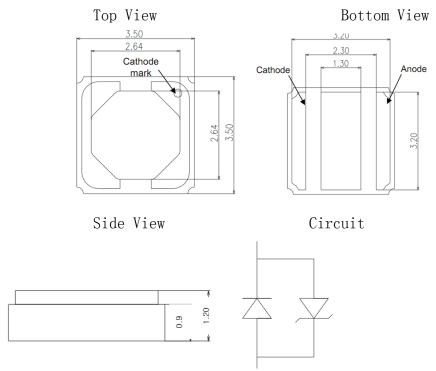
Specification

Outline dimensions



Notes:

- [1] All dimensions are in millimeters.
- [2] Scale: none
- [3] Undefined tolerance is ± 0.2 mm

Characteristics

* Electro-Optical characteristics at 20mA

(Ta=25°C, RH=30%)

Parameter	Symbol	Value	Unit
Peak wavelength [1]	λp	275	nm
Radiant Flux[2]	Фе [3]	1.8	mW
Forward Voltage [4]	VF	6. 0	V
Spectrum Half Width	Δλ	11	nm
View Angle	$2\Theta 1/2$	_	deg.
Thermal resistance	R θ J-b[5]	_	°C /W

* Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Forward Current	IF	30	mA
Power Dissipation	PD	200	mW
Operating	Topr	-30 ~ +60	°C
Temperature			
Storage	Tstg	-40 [~] +100	°C
Temperature			

Notes:

- 1. Peak Wavelength Measurement tolerance : ± 3 nm
- 2. Radiant Flux Measurement tolerance : \pm 10%
- 3. Φe is the Total Radiant Flux as measured with an integrated sphere.
- 4. Forward Voltage Measurement tolerance : $\pm 3\%$
- 5. R θ J-bis the thermal resistance between chip junction to PCB board bottom. The PCB is made of aluminium and the size of PCB is 3.5mm by 3.5mm